# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computer

**Marketing Name / Model**
[List multiple models if applicable.]

HP Envy Rove 20 Mobile All-in-One PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MotherBoard/Convertor board/Control board/Audio board/Usb board/Card Reader board</td>
<td>6</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery&amp;RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td>TORX T8</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removed Btn Cover
2. Removed Rear Cover
3. Removed HDD module --> Sub: remove HDD Rubber
4. Removed MB Shielding
5. Removed Hinge Recess
6. Removed Hinge Cap L&R
7. Removed Stand
8. Removed Card reader board
9. Removed Control board
10. Removed Convertor board
11. Removed Speaker module
12. Removed AD board
13. Removed Usb board
14. Removed Audio board
15. Removed Thermal module
16. Removed Battery
17. Removed MB
18. Removed Middle frame
19. Removed LCD panel
20.
21.
22.
23.
24.
25.
26.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly

Step 1. Removed Btn Cover

Step 2. Removed Rear Cover
Step 3. Removed HDD module
--> Sub: remove HDD Rubber

Step 4. Removed MB Shielding

Step 5. Removed Hinge Recess

Step 6. Removed Hinge Cap L&R

Step 7. Removed Stand

Step 8. Removed Card reader board

Step 9. Removed Control board

Step 10. Removed Convertor board
Step 11. Removed Speaker module

Step 12. Removed AD board

Step 13. Removed USB board

Step 14. Removed Audio board

Step 15. Removed Thermal module

Step 16. Removed Battery

Step 17. Removed MB

Step 18. Removed Middle frame

Step 19. Removed LCD pane